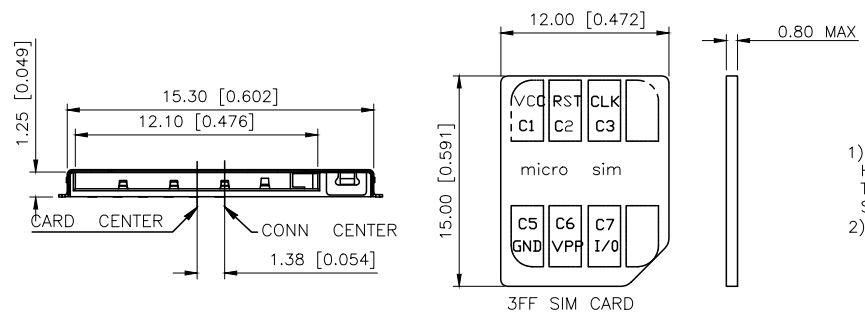
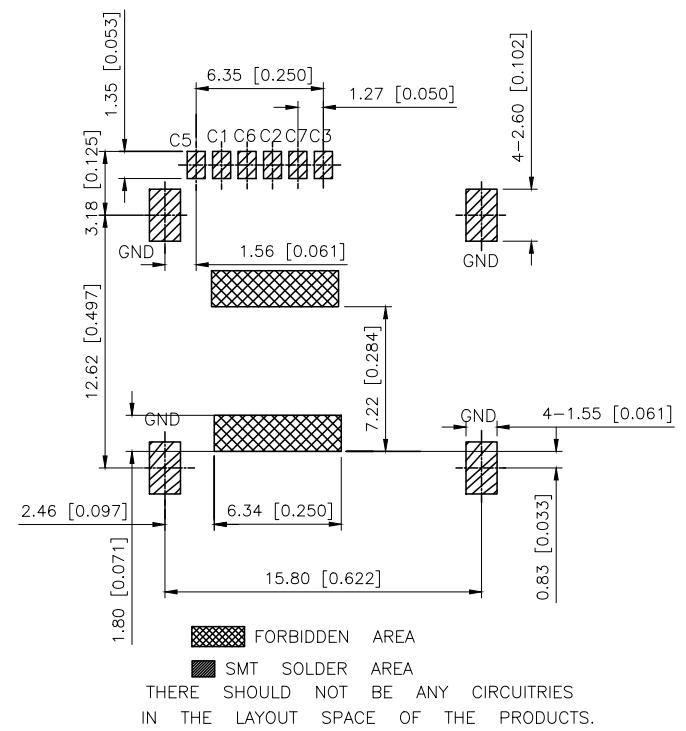
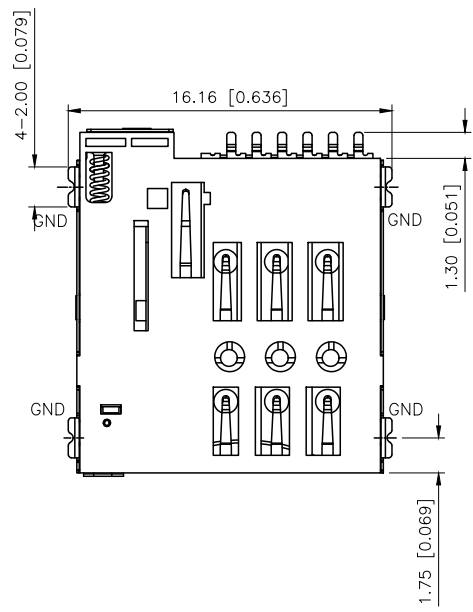
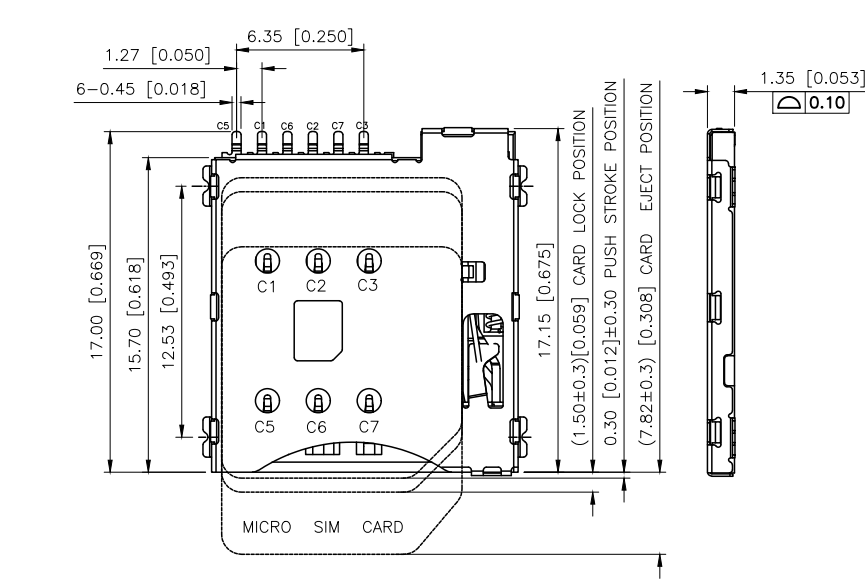


REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.15	阿树



1)MATERIAL:
HOUSING:HI-TEMP. PLASIC UL 94V-0
TERMINAL:COPPER ALLOY
SHELL:SUS
2)FINISH:
CONTACT:GOLD FLASH PLATED ON CONTACT AREA;
GOLD FLASH PLATED ON SOLDER TAILS,

③	Shell	1	SUS	
②	Terminal	6	COPPER ALLOY	
①	Housing	1	HI-TEMP.PLASIC UL 94V-0	BLACK
ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



DESIGN	阿树	VIEW:	MODEL TYPE: SIM CARD CONN
CHECKED		UNIT: mm/in	PART NO.: XKSIM-114
APPROVED		SIZE: A4	DWG NO.: